



Device Material Content

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Package: 100 PQFP with SnPb Plating
Total Device Weight 1.60 Grams

MSL: 3
Peak Reflow Temp: 225°C

August, 2008	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	1.11%	0.018			Silicon chip	7440-21-3	Die size: 3.38 x 3.54 x 0.64 mm
Mold	84.19%	1.347	73.84%	1.181	Silica Fused	60676-86-0	Mold Compound Density varies between 1.7 and 2.3 grams/cc 75 to 95% Silica Fused (LSC uses 87.7% in our calculation) 4 to 10% Epoxy Resin (LSC uses 7% in our calculation). 2 to 8% Phenol Resin (LSC uses 5% in our calculation). 0.1 to 0.5% Carbon black (LSC uses 0.3% in our calculation)
			5.89%	0.094	Epoxy Resin	-	
			4.21%	0.067	Phenol Resin	-	
			0.25%	0.004	Carbon black	1333-86-4	
D/A Epoxy	0.08%	0.0012	0.061%	0.0010	Silver-filled Epoxy	7440-22-4	Die attach epoxy Density: 4 grams/cc (silver content: 70-90%; LSC uses 80% in our calculation)
			0.015%	0.0002	Silver (Ag) other	-	
Wire	0.26%	0.004			Gold (Au)	7440-57-5	1.0 mil wire diameter; 1 wire for each package lead; wire length 3 mm
Lead Plating	1.48%	0.024	1.26%	0.020	Tin (Sn)	7440-31-5	Nominal: 85% Sn, 15% Pb Thickness is 0.015mm
			0.22%	0.004	Lead (Pb)	7439-92-1	
Leadframe	12.88%	0.206	12.39%	0.198	Copper (Cu)	7440-50-8	Leadframe thickness is nominal (per Case Outline) 96.2% Cu 3.0% Ni 0.65% Si 0.15% Mg
			0.39%	0.0062	Nickel (Ni)	7440-02-0	
			0.08%	0.0013	Silicon (Si)	7440-21-3	
			0.02%	0.0003	Magnesium (Mg)	7439-95-4	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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